



转移生带

41110-T

TRANSFER TAPE

适用于96%氧化铝基板、介电常数为~4的无铅转移生瓷带
Lead-Free Ceramic Transfer Tape with Dielectric Constant ~ 4 for
Use with 96% Alumina Substrates

ESL41110-T是由分散于有机基体中的无机介质粉末，经过层压和烧结，在氧化铝基板上形成的柔性挤塑薄膜。在压强为1.7-6.9MPa，温度为70℃的条件下，层压该生带效果最好。层压后，零部件在带式烧结炉中进行烧结。ESL建议在峰值温度为580℃，周期为50分钟的条件下进行烘干排胶，然后在峰值温度为850℃，周期为45分钟的条件下进行烧结。对层压和烧结的多层生带逐步进行金属化可以形成多层零部件。该产品适用于低介电常数和低损耗的领域中。此转移生带被定型在硅涂层聚酯薄膜上，以减小环境污染，防止其受到机械损伤，且便于操作处理。

A flexible cast film of inorganic dielectric powder dispersed in an organic matrix, designed to be laminated to and fired on an alumina substrate. A pressure/temperature combination of 1.7-6.9 MPa and 70°C works well for laminating this tape. After lamination, the parts can be fired in a belt furnace at 580°C peak/50 minute cycle burnout followed by an 850°C peak/45 minute cycle for sintering. Multilayer parts can be formed by metallizing laminated and fired sheets progressively. This tape is useful when low dielectric constant and low loss are desired. Transfer tape is provided on a silicone-coated polyester film to minimize environmental contamination, to protect it from mechanical damage, and to aid in handling.

产品特性 PROPERTIES (when laminated and fired on 96% Al₂O₃)

介电常数	DIELECTRIC CONSTANT:(1 MHz)(using 803)	4.0-5.0	
耗散因数	DISSIPATION FACTOR:(1 MHz)	≤ 0.4%	
绝缘电阻	INSULATION RESISTANCE: (at 100 VDC, 25°C)	≥ 10 ¹² Ω/□	
热导率	THERMAL CONDUCTIVITY:	2.5-3.0 W/m/°C	
击穿电压	BREAKDOWN VOLTAGE:	> 1200 V/25 μm	
高压试验	PRESSURE COOKER:(Insulation resistance after 15 minutes at 2 atmospheres)	≥ 10 ¹² Ω/□	
烧结收缩率	FIRED SHRINKAGE:(Using recommended processing parameters)	X and Y	0 %
		Z	45-55 %
烧结密度	FIRED DENSITY:(Theoretical)	2.26 g/cm ³	
生带厚度	TAPE THICKNESS:	115-135 μm	
颜色	COLOR: light Blue	浅蓝色	
保质期	SHELF LIFE: (when stored in dry N ₂)	6个月	
推荐用导体浆料	RECOMMENDED CONDUCTORS:	ESL 903-A, 903-C, 902, 803, 963	

Dielectric Constant vs. Freq

